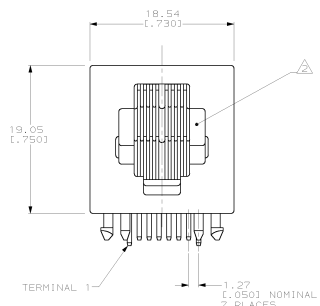
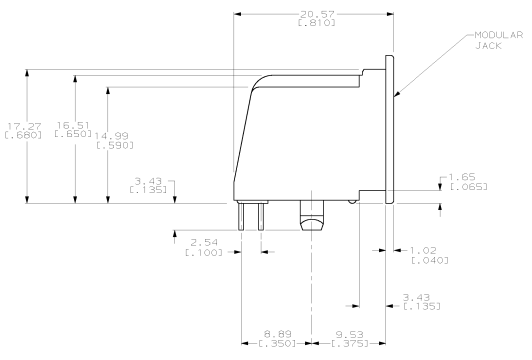
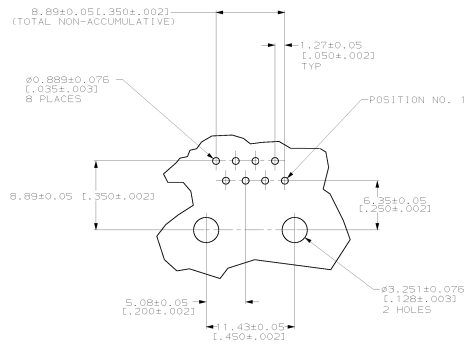
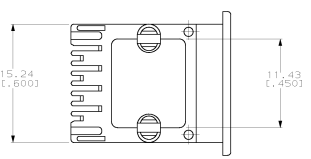


REV	DATE	DESCRIPTION	BY	CHK	APP
AA	22				
1		SUPERSEDED BY EC 0074-0046-99			

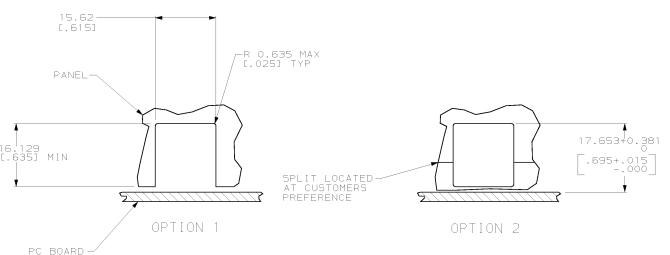


⚠ MATERIAL: HOUSING - PBT POLYESTER, BLACK. TERMINAL - 0.38 (.014) THICK PHOS BRONZE PLATED WITH 1.27µm (.000050) THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA & 3.81µm (.000150) THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm(.000050) THICK NICKEL UNDERPLATE.

⚠ CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, FC-76 SPECIFICATIONS FOR MODULAR TELEPHONE HARDWARE.



PRINTED CIRCUIT BOARD LAYOUT  
VIEW SHOWN FROM CIRCUIT SIDE



PANEL CUTOUT  
SCALE 2:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		BY: J. JONES	DATE: 08/04/88	REV: 1	APP: [Signature]
SUPERSEDED BY 520243-4		CONTACTS		PART NUMBER	
SUPERSEDED BY 520243-3		CONTACTS		PART NUMBER	
AMPI Incorporated		Harrisburg, PA 17105-3608		PRINTED CIRCUIT BOARD	
108-1163		114-2048		MODULAR JACK ASSEMBLY, SIDE ENTRY, 8 POSITION, FLANGED	
A1 00778		520243		REVISED	
CUSTOMER DRAWING		SCALE: 2:1		SHEET: 1 OF 1	